

12-22-2000

U.S. DEPARTMENT OF COMMERCE
Patent and Trademark Office



HEET

101558329

Attorney's Docket No. 027260-414

To the Honorable Commissioner of Patents and Trademarks. Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

Yoshihiro SHIMIZU, Shinji TAKEDA and Sachiko KAWAGUCHI

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

3. Nature of conveyance:

☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name

Other: _____

Execution Date: November 7, 2000

2. Name and address of receiving party(ies):

Name: SEE ATTACHED

Address: _____

Additional name(s) & address(es) attached? ☐ Yes ☒ No

4. Application number(s) or patent number(s):

09/730841

If this document is being filed together with a new application, the execution date of the application is: November 7, 2000

A. Patent Application No.(s)

TBA

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Platon N. Mandros

Address: BURNS, DOANE, SWECKER & MATHIS, L.L.P.

P.O. Box 1404

Alexandria, Virginia 22313-1404

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR § 3.41): \$ 40.00

☒ Enclosed

☒ Authorized to be charged to deposit account, if necessary

8. Deposit account number:

02-4800

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and the attached copy is a true copy of the original document.

Platon N. Mandros
Name of Person Signing

Signature

December 7, 2000
Date

Total number of pages including cover sheet, attachments, and document: 4

Mail documents to be recorded with required cover sheet information to:

Commissioner of Patents and Trademarks
Box Assignments
Washington, D.C. 20231

12/11/2000 MMARMOL 00000018 09730841
40.00 OP

02 FC:581

ATTACHMENT

Title:

"MICROCOMPUTER CAPABLE OF MAKING EFFECTIVE USE OF LOW
CURRENT CONSUMPTION MODE"

Assignee(s):

1. MITSUBISHI DENKI KABUSHIKI KAISHA

Address: 2-3, Marunouchi 2-chome, Chiyoda-ku, Tokyo 100-8310 Japan

2. MITSUBISHI ELECTRIC SYSTEM LSI DESIGN CORPORATION

Address: 1-17, Chuo 3-chome, Itami-shi, Hyogo 664-0851 Japan

3. MITSUBISHI ELECTRIC SEMICONDUCTOR SYSTEM CORPORATION

Address: 4-1, Hamamatsu-cho 2-chome, Minato-ku, Tokyo 105-6130 Japan

ASSIGNMENT

(JOINT)

THIS ASSIGNMENT, by Yoshihiro SHIMIZU of Hyogo, Japan;
Shinji TAKEDA of Tokyo, Japan and Sachiko KAWAGUCHI of Hyogo, Japan ~~and~~
~~residing at~~
 and _____
 respectively, witnesseth: _____ (hereinafter referred to as "the Assignors"),

WHEREAS, the Assignors have invented certain new and useful improvements in
See the attachment set forth in an
 application for Letters Patent of the United States, [] which is a provisional application to be filed
 herewith; [x] which is a non-provisional application having an oath or declaration executed on even
 date herewith prior to filing of application; [] bearing Application No. _____
 and filed on _____; and

WHEREAS, See the attachment
 a corporation duly organized under and pursuant to the laws of Japan and having its
 principal place of business at See the attachment
 _____ (hereinafter referred to as "the Assignee"), is desirous of acquiring the
 entire right, title, and interest in and to said inventions, the right to file applications on said
 inventions and the entire right, title and interest in and to any applications, including provisional
 applications for Letters Patent of the United States or other countries claiming priority to said
 application, and in and to any Letters Patent or Patents, United States or foreign, to be obtained
 therefor and thereon.

NOW, THEREFORE, in consideration of One Dollar (\$1.00) and other good and
 sufficient consideration, the receipt of which is hereby acknowledged, the Assignors have sold,
 assigned, transferred, and set over, and by these presents do sell, assign, transfer, and set over,
 unto the Assignee, its successors, legal representatives, and assigns the entire right, title, and
 interest in and to the above-mentioned inventions, the right to file applications on said inventions
 and the entire right, title and interest in and to any applications for Letters Patent of the United
 States or other countries claiming priority to said applications, and any and all Letters Patent or
 Patents of the United States of America and all foreign countries that may be granted therefor and
 thereon, and in and to any and all applications claiming priority to said applications, divisions,
 continuations, and continuations-in-part of said applications, and reissues and extensions of said
 Letters Patent or Patents, and all rights under the International Convention for the Protection of
 Industrial Property, the same to be held and enjoyed by the Assignee, for its own use and behalf
 and the use and behalf of its successors, legal representatives, and assigns, to the full end of the
 term or terms for which Letters Patent or Patents may be granted as fully and entirely as the same
 would have been held and enjoyed by the Assignors had this sale and assignment not been made;

AND for the same consideration, the Assignors hereby covenant and agree to and with
 the Assignee, its successors, legal representatives, and assigns, that, at the time of execution and
 delivery of these presents, the Assignors are the sole and lawful owners of the entire right, title,
 and interest in and to the inventions set forth in said applications and said applications, including
 provisional applications, above-mentioned, and that the same are unencumbered, and that the
 Assignors have good and full right and lawful authority to sell and convey the same in the manner
 herein set forth;

AND for the same consideration, the Assignors hereby covenant and agree to and with the Assignee, its successors, legal representatives, and assigns that the Assignors will, whenever counsel of the Assignee, or the counsel of its successors, legal representatives, and assigns, shall advise that any proceeding in connection with said inventions or said applications for Letters Patent or Patents, or any proceeding in connection with Letters Patent or Patents for said inventions in any country, including interference proceedings, is lawful and desirable, or that any application claiming priority to said application, division, continuation, or continuation-in-part of any applications for Letters Patent or Patents, or any reissue or extension of any Letters Patent or Patents to be obtained thereon, is lawful and desirable, sign all papers and documents, take all lawful oaths, and do all acts necessary or required to be done for the procurement, maintenance, enforcement, and defense of Letters Patent or Patents for said inventions, without charge to the Assignee, its successors, legal representatives, and assigns, but at the cost and expense of the Assignee, its successors, legal representatives, and assigns;

AND the Assignors hereby authorize and request the attorneys of BURNS, DOANE, SWECKER & MATHIS, L.L.P. of Alexandria, Virginia, to insert in the spaces provided above the filing date, application number, and attorney docket number of said application when known.

AND the Assignors hereby request the Commissioner of Patents to issue any and all said Letters Patent of the United States to the Assignee as the Assignee of said inventions, the Letters Patent to be issued for the sole use and behalf of the Assignee, its successors, legal representatives, and assigns.

Date	<u>November 7, 2000</u>	Name of Assignor	<u>Yoshihiro Shimizu</u> Yoshihiro SHIMIZU
Date	<u>November 7, 2000</u>	Name of Assignor	<u>Shinji Takeda</u> Shinji TAKEDA
Date	<u>November 7, 2000</u>	Name of Assignor	<u>Sachiko Kawaguchi</u> Sachiko KAWAGUCHI
Date	_____	Name of Assignor	_____
Date	_____	Name of Assignor	_____
Date	_____	Name of Assignor	_____
Date	_____	Name of Assignor	_____
Date	_____	Name of Assignor	_____

ATTACHMENT

Title

"MICROCOMPUTER CAPABLE OF MAKING EFFECTIVE USE OF LOW CURRENT
CONSUMPTION MODE"

Assignee(s)

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